



# SPECIFICATION

- · Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N :
- CL10A475KQ8NNNL

(Reference sheet)

- · Description :
- CAP, 4.7uF, 6.3V, ±10%, X5R, 0603

A. Samsung Part Number

		<u>CL</u> ①	<u>10</u> ②	<u>А</u> З	<u>475</u> ④	<u>K</u> 5	<mark>Q</mark> 6	<u>8</u> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>∟</u> 10
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0603 (inch co	de)		L: 1	1.60	± 0.10	mm			W:	$0.80 \pm 0.10$ mm
3	Dielectric	X5R				8	Inner	elect	rode			Ni
4	Capacitance	4.7 uF					Term	inatio	n			Cu
5	Capacitance	±10 %					Platin	g				Sn 100% (Pb Free)
	tolerance					9	Produ	uct				Normal
6	Rated Voltage	6.3 V				10	Speci	al				Reserved for future use
1	Thickness	$0.80 \pm 0.10$ mm				1	Packa	aging				Cardboard Type, 13" reel

### **B. Structure & Dimension**



Samsung P/N	Dimension(mm)							
Samsung F/N	L	W	Т	BW				
CL10A475KQ8NNNL	1.60 ± 0.10	0.80 ± 0.10	0.80 ± 0.10	0.30 ± 0.20				

#### C. Samsung Reliablility Test and Judgement Condition

WithstandingNo dielectric breamechanical	100Mohm× <i>μ</i> F	1kHz ±10% / 1.0±0.2Vrms   *A capacitor prior to measuring the capacitance is heat treated at 150°C+0/-10°C for 1 hour and maintained in ambient air for 24±2 hours.   Rated Voltage 60~120 sec.				
Insulation10,000Mohm orResistanceWhichever is snAppearanceNo abnormal extWithstandingNo dielectric breadVoltagemechanical breadTemperatureX5RCharacteristics(From-55 °C to 85)Adhesive StrengthNo peeling shallof Terminationterminal electrodBending StrengthCapacitance chasSolderabilityMore than 75% of		treated at 150 °C +0/-10 °C for 1 hour and maintained in ambient air for 24±2 hours.				
ResistanceWhichever is smAppearanceNo abnormal extWithstandingNo dielectric breadVoltagemechanical breadTemperatureX5RCharacteristics(From-55 °C to 85)Adhesive StrengthNo peeling shallof Terminationterminal electrodBending StrengthCapacitance characteristicsSolderabilityMore than 75% contracteristics		Rated Voltage 60~120 sec				
AppearanceNo abnormal extWithstandingNo dielectric breadVoltagemechanical breadTemperatureX5RCharacteristics(From-55 °C to 85)Adhesive StrengthNo peeling shallof Terminationterminal electrodBending StrengthCapacitance chainSolderabilityMore than 75% contraction	naller					
WithstandingNo dielectric breamechanical						
Voltagemechanical breaTemperatureX5RCharacteristics(From-55 °C to 85)Adhesive StrengthNo peeling shallof Terminationterminal electrodBending StrengthCapacitance chaSolderabilityMore than 75% contact	erior appearance	Microscope (×10)				
TemperatureX5RCharacteristics(From-55 °C to 88)Adhesive StrengthNo peeling shallof Terminationterminal electrodBending StrengthCapacitance chaSolderabilityMore than 75% c	akdown or	250% of the rated voltage				
Characteristics(From-55 °C to 85Adhesive StrengthNo peeling shallof Terminationterminal electrodBending StrengthCapacitance charSolderabilityMore than 75% c	kdown					
Adhesive Strength of TerminationNo peeling shall terminal electrodBending StrengthCapacitance chaSolderabilityMore than 75% c						
of Terminationterminal electrodBending StrengthCapacitance chaSolderabilityMore than 75% c	5℃, Capacitance change s	hould be within ±15%)				
Bending StrengthCapacitance chaSolderabilityMore than 75% c	be occur on the	500g⋅f, for 10±1 sec.				
Solderability More than 75% of	le					
,	ange : within ±12.5%	Bending to the limit (1mm)				
,		with 1.0mm/sec.				
is to be soldered	of terminal surface	SnAg3.0Cu0.5 solder				
	newly	245±5°C, 3±0.3sec.				
		(preheating : 80~120℃ for 10~30sec.)				
Resistance to Capacitance cha	ange: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering Heat Tan δ, IR : initial						
Vibration TestCapacitance chaTan δ, IR : initial	•	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)				
Moisture Capacitance cha	inge: within ±12.5%	With rated voltage				
<b>Resistance</b> Tan $\delta$ : 0.125	max	40±2°C, 90~95%RH, 500+12/-0hrs				
IR : 500Mot	nm or 12.5Mohm × <i>µ</i> F					
Whiche	ver is smaller					
High Temperature Capacitance cha	ange : within ±12.5%	With 150% of the rated voltage				
<b>Resistance</b> Tan $\delta$ : 0.125	max	Max. operating temperature				
IR : 1,000M	ohm or 25Mohm × $\mu$ F	1000+48/-0hrs				
Whiche	ver is smaller					
Temperature Capacitance cha	ange: within ±7.5%	1 cycle condition				
<b>Cycling</b> Tan δ, IR : initial	spec.	Min. operating temperature $\rightarrow 25^{\circ}C$				
		$\rightarrow$ Max. operating temperature $\rightarrow$ 25°C				
		$\sim$ max. Operating temperature $\rightarrow$ 25 C				

X The reliability test condition can be replaced by the corresponding accelerated test condition.

## D. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time.

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Should you have any question regarding the product specifications,

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- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- ④ Military equipment
- *⑤* Disaster prevention/crime prevention equipment
- *ⓐ* Any other applications with the same as or similar complexity or reliability to the applications set forth above.